



Inputs from WG2

SVT coordination meeting

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PED request:

We would consider (for the groups that do not have yet dedicated in-kind funds for this), to request support for buying the readout units for performing DAQ-based tests of the sensors (for wafer-probe based tests, dedicated equipment is required, which includes 12-inches wafer prober + dedicated probe cards)

Basic equipment needed:

- Enclustra Mercury+ PE1 300 board containing a AA1 SoC Module is current the best option
- ~ 20 kUSD would be needed to support institutes wanting to buy the setup for testing (4-5 institutes)

SVT workfest at Lehigh meeting (https://www.jlab.org/eicug-epic)

- Total of 2hours
- (20+10 min) General status of the WP2 testing and characterization activities (Lukas, GMI)
 - present the updated version of the activity summary
 - discuss workforce and areas that need more support
 - groups involved and areas of involvement
 - timescales for the various testing phases of MOSAIX, LAS, ancillary chips
- (20+10 min) Status/plans of the software development for MOSAIX, LAS, ancillary chips
- (20+10 min) Status/plans of the firmware/hardware development for MOSAIX, LAS, ancillary chips
- (20+10 min) Discussion on TDR preparation
 - we will prepare a draft of the TDR topics related to WG2

Preparation for the TDR:

- currently working on a skeleton of the TDR content
- we would aim to have 2-3 pages (WG2-only)
- plan is to have a skeleton for the Lehigh's meeting